

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

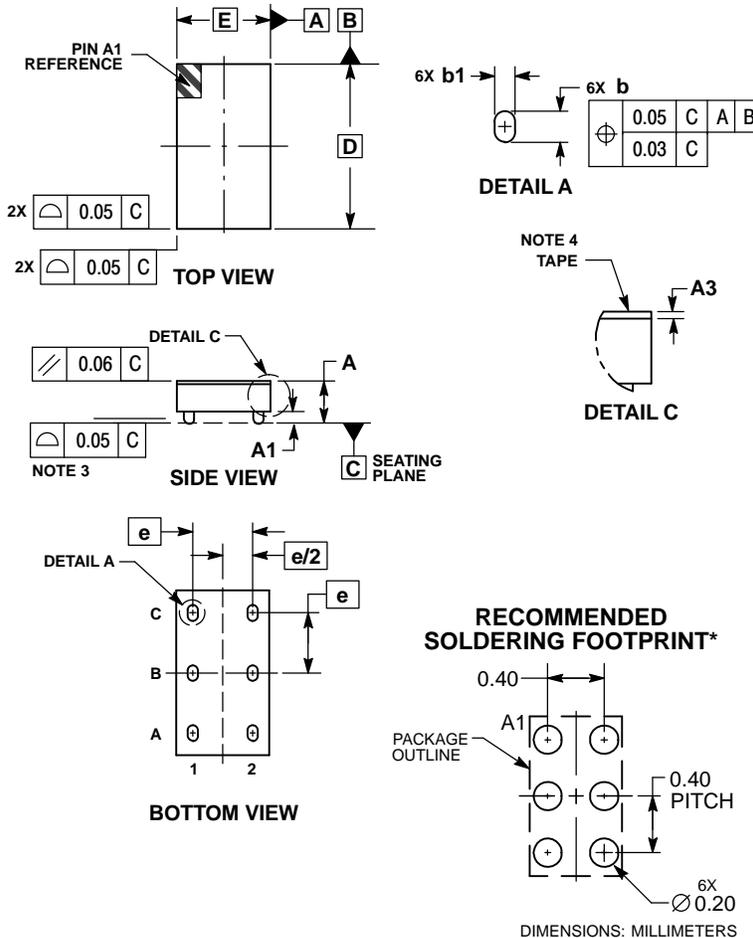
ON Semiconductor®



SCALE 4:1

WLCSP6, 1.097x0.622
CASE 567NZ
ISSUE A

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- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
 4. BACKSIDE TAPE APPLIED TO IMPROVE PIN 1 MARKING.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.295	0.335	0.375
A1	0.065	0.090	0.115
A3	0.025 REF		
b	0.125	0.150	0.175
b1	0.075	0.100	0.125
D	1.047	1.097	1.147
E	0.572	0.622	0.672
e	0.40 BSC		

GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP6, 1.097X0.622	PAGE 1 OF 2

